#### 



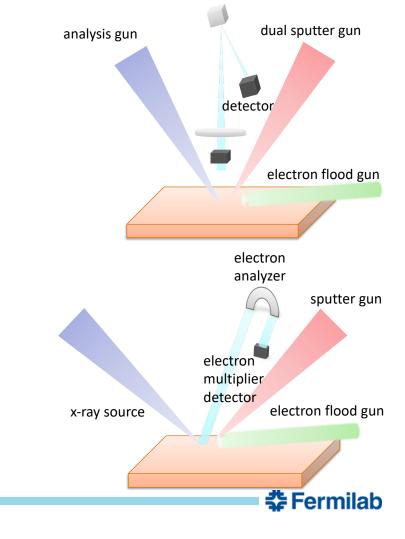
#### **Chemical Characterization Techniques of Qubits**

#### **Akshay Murthy**

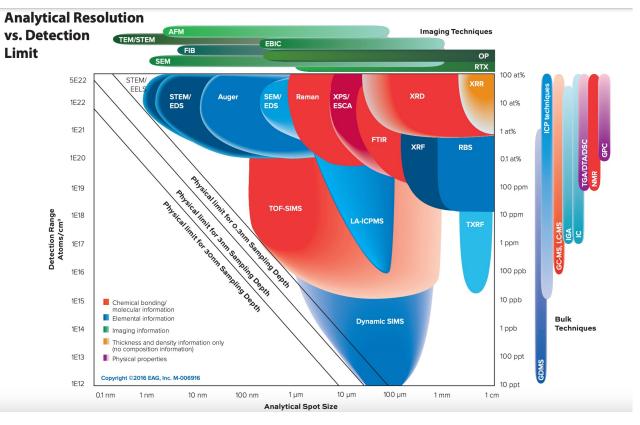
Group Leader, Materials for Quantum Devices Deputy Head, Qubits and Materials Department, SQMS Division August 14<sup>th</sup>, 2023

## Outline

- Overview of Chemical Characterization Techniques
- Time of Flight Secondary Ion Mass Spectrometry (ToF-SIMS)
- X-ray Photoelectron Spectroscopy (XPS)



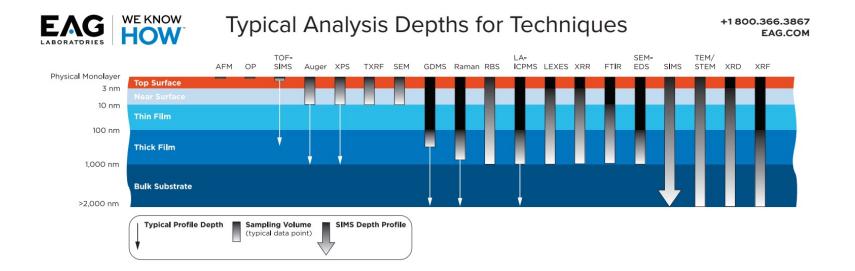
## **Chemical Characterization Techniques**



Source: EAG

**7** Fermilab

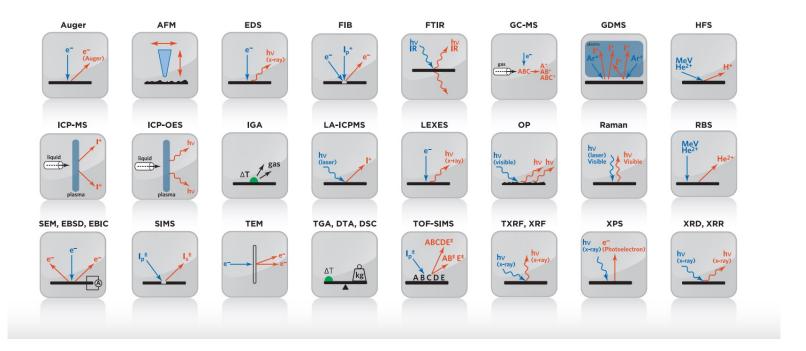
### **Chemical Characterization Techniques**



Source: EAG



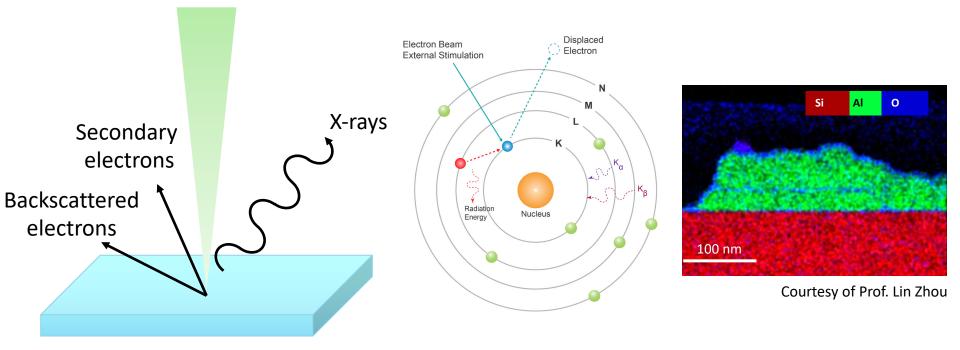
## **Chemical Characterization Techniques**



Source: EAG

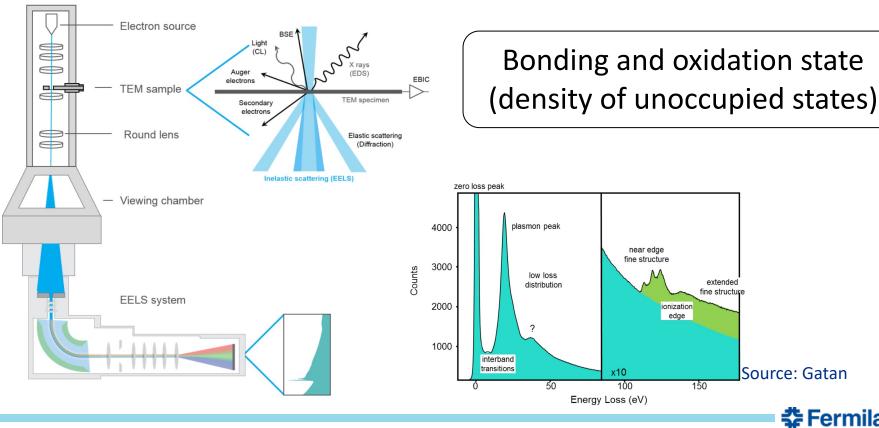


## **Chemical Characterization Techniques - EDS**





## **Chemical Characterization Techniques - EELS**



extended

fine structure

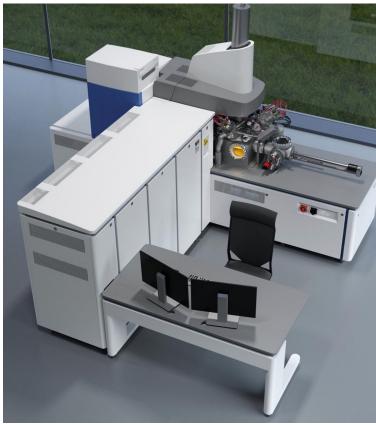
Source: Gatan

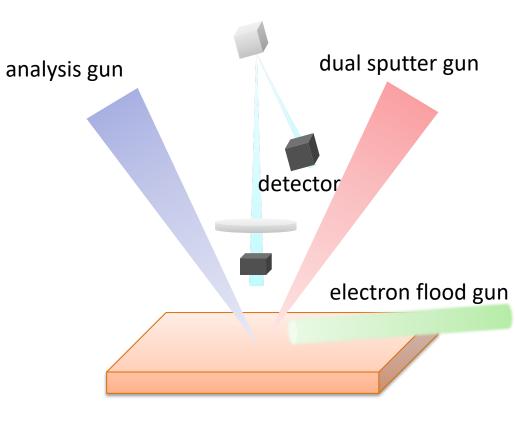
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ionization edge

150

#### **ToF-SIMS**

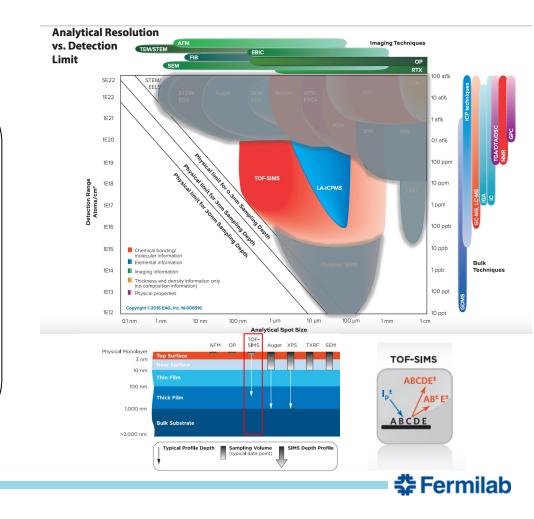






## **ToF-SIMS: Basics**

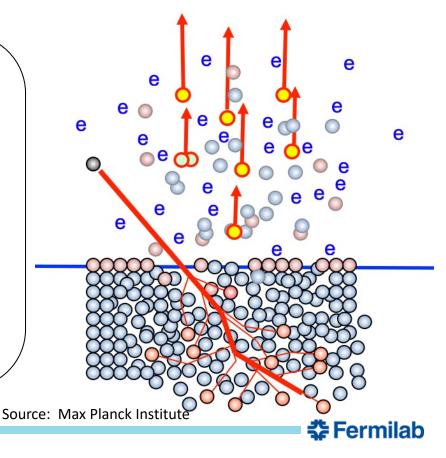
- Very sensitive surface
  analytical technique
- Provides elemental & molecular information
- 3D analysis
- Detection of low atomic number elements



## **ToF-SIMS: Surface Bombardment**

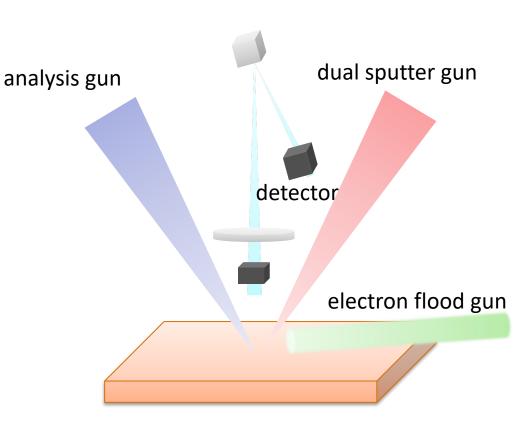
- Surface is bombarded by 30 keV primary ions
- Primary ion energy transferred to surface atoms and molecular compounds through atomic collisions

 $\rightarrow$  secondary ions overcome surface binding energy



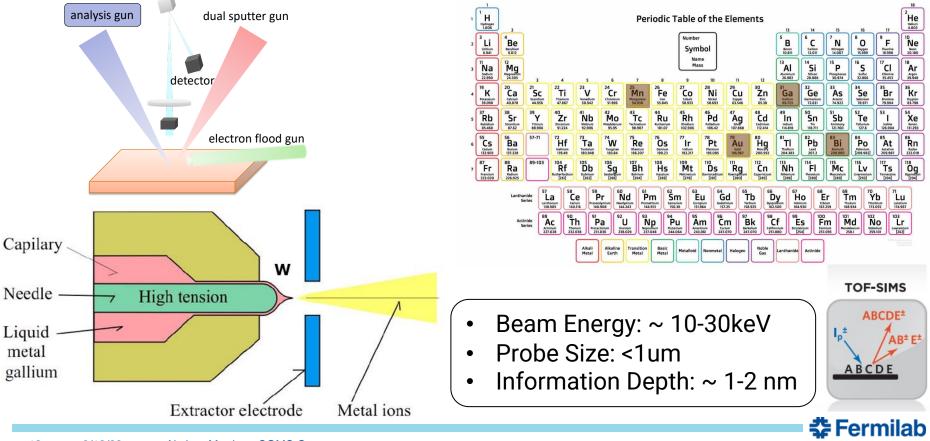
## **ToF-SIMS**

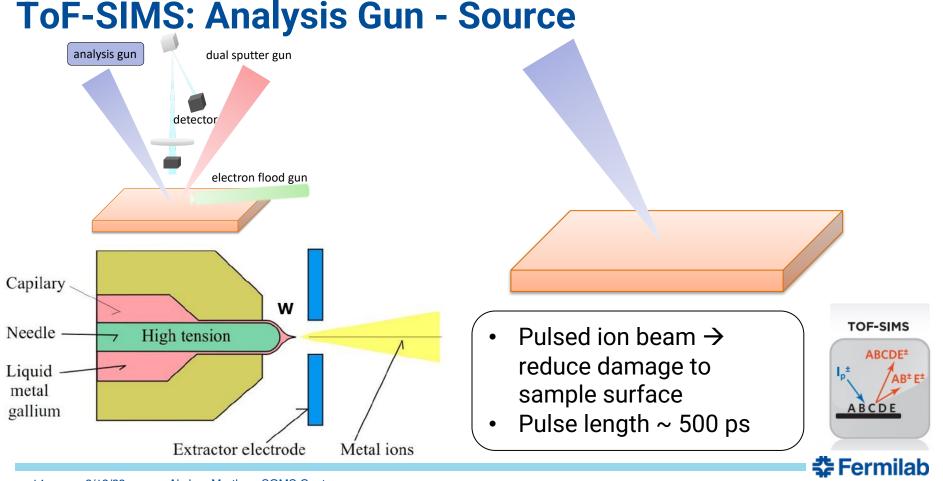
- Analysis gun
- Dual sputter gun
- Electron flood gun
- Detector



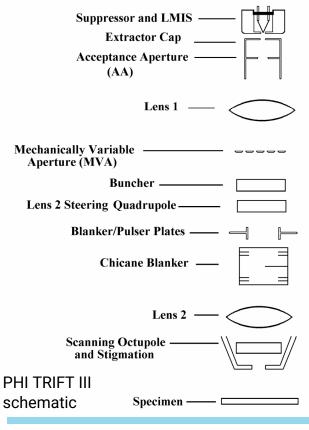


#### **ToF-SIMS: Analysis Gun - Source**





## **ToF-SIMS: Analysis Gun - Optics**



<u>Extractor</u>: Accelerating voltage used to extract ions from source and generate ion beam

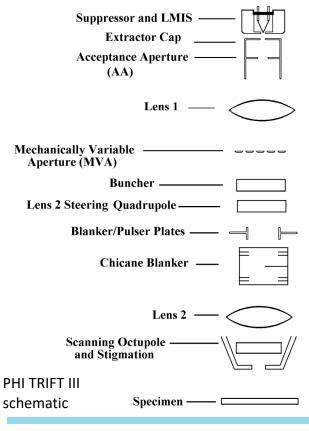
<u>Suppressor</u>: Voltage used to improve distribution of extracted ions

Lens 1 (Condenser Lens): Parallelizes ion beam to form an ion probe

<u>Mechanically Variable Aperture</u>: Defines ion current – array of apertures used to set probe size



## **ToF-SIMS: Analysis Gun - Optics**



<u>Blanker/Pulser Plates</u>: Pulses ion beam to reduce surface damage

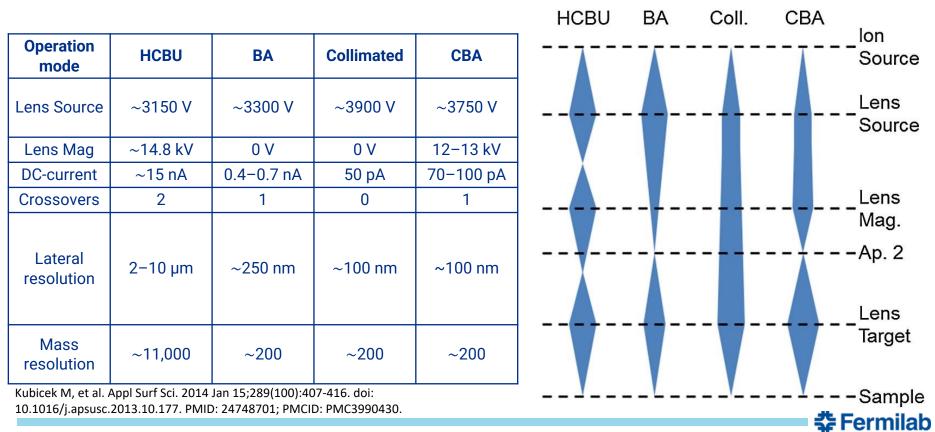
Lens 2 (Objective Lens): Focuses ion beam onto sample

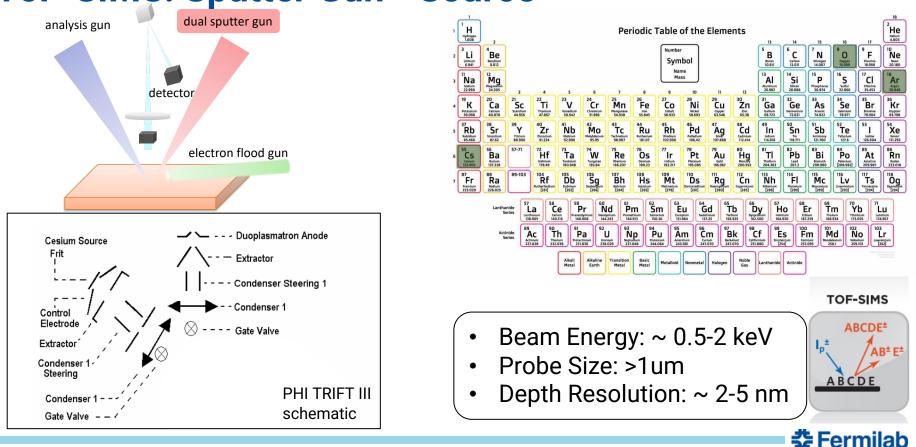
<u>Scanning Octupole</u>: Allows for rastering ion beam across region of interest

<u>Stigmation:</u> Applies weak electric field to reduce astigmatism in ion beam



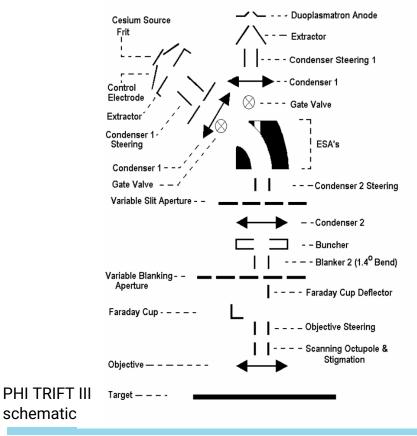
## **ToF-SIMS: Analysis Gun – Different Modes**





#### **ToF-SIMS: Sputter Gun - Source**

#### **ToF-SIMS: Sputter Gun - Optics**

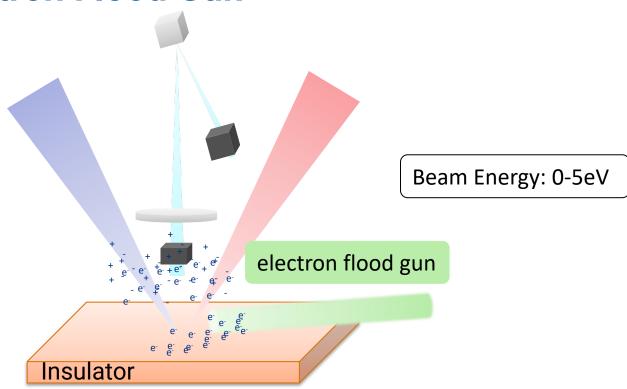


Similar to analysis gun optics



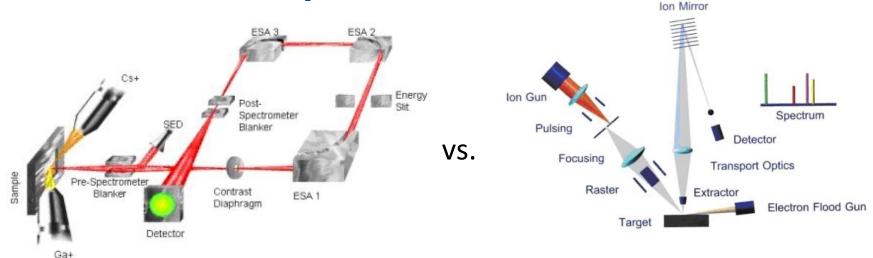
schematic

#### **ToF-SIMS: Electron Flood Gun**





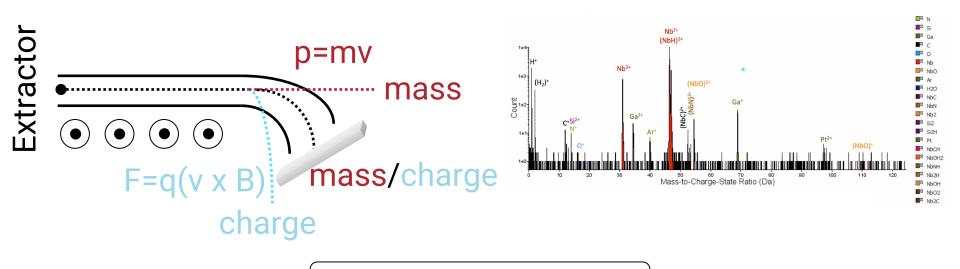
#### **ToF-SIMS: Mass Spectrometer – Flight Path**



- Secondary ions directed using an extractor
- 2 main options in terms of flight paths:
  - Circular vs Linear



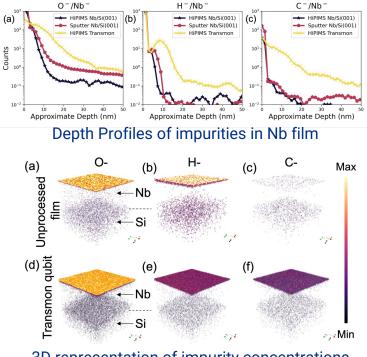
#### **ToF-SIMS: Detector – Mass Spectrometer**



Detector measures m/z ratio



# **Highlight: Quantifying Impurities in Nb Qubit Films**

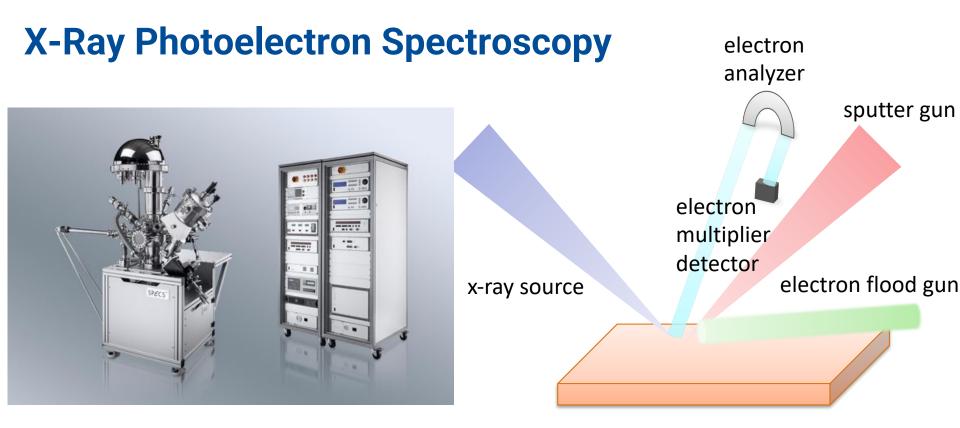


3D representation of impurity concentrations

- TOF-SIMS applied for the first time ever to 2D qubits reveal levels of contamination in the Nb pads
- Lithography steps during qubit fabrication lead to incorporation of impurity species including O<sup>-</sup>, H<sup>-</sup>, C<sup>-</sup>, Cl<sup>-</sup>, F<sup>-</sup>, Na<sup>+</sup>, Mg<sup>+</sup>, and Ca<sup>+</sup>
- Evaluating possible effects of the film purity on the microwave dissipation

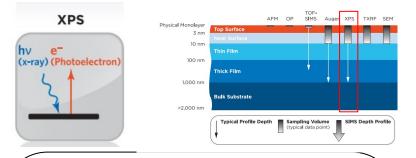
Appl. Phys. Lett. 120 (4), 044002 (2022)



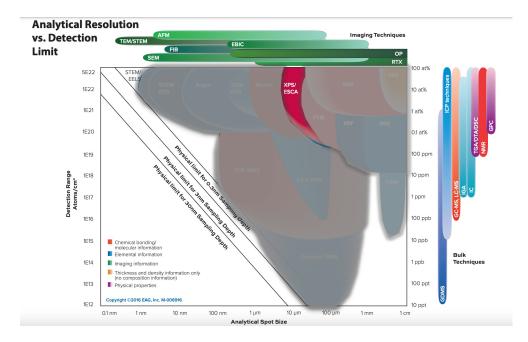




### **XPS Basics**



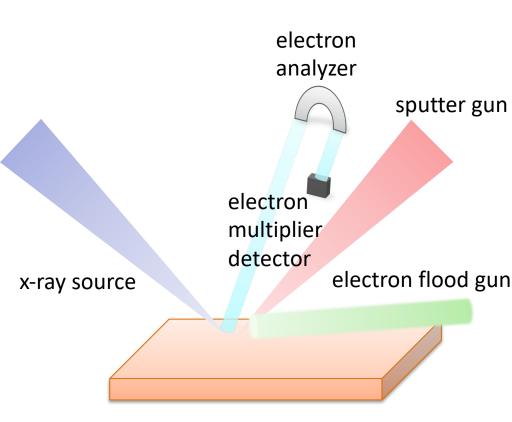
- Sensitive to atom%
- Provides elemental & bonding information
- Detection of low atomic number elements





# **XPS Components**

- X-Ray Source
- Sputter gun
- Electron flood gun
- Electron detector

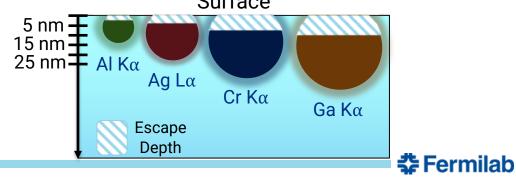




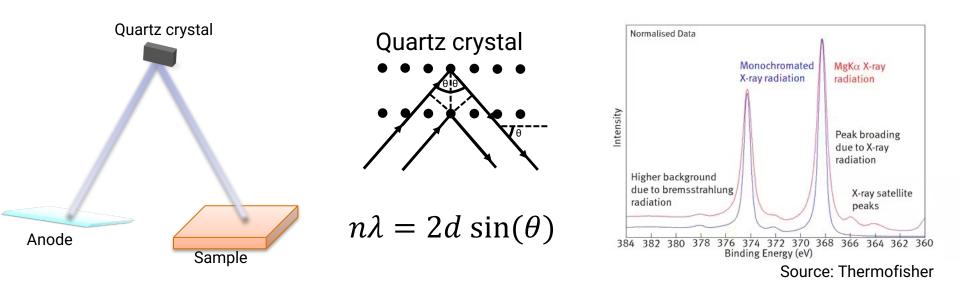
### **XPS: X-Ray Source**



- Probe Size: ~500 um
- Information Depth: ~ 5-15 nm

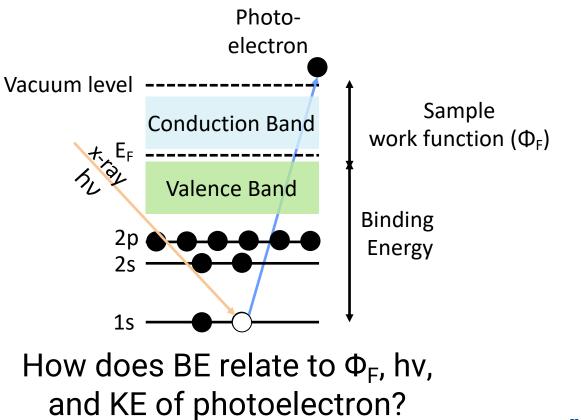


## **XPS: X-Ray Monochromator**





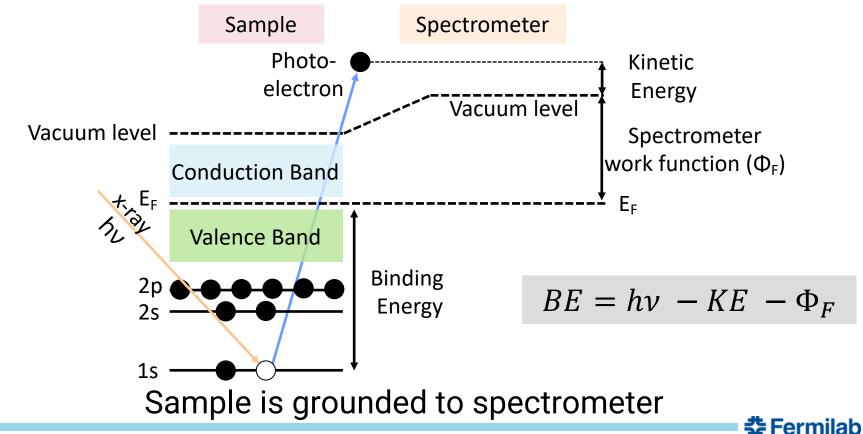
## **XPS: Photoelectric Effect**



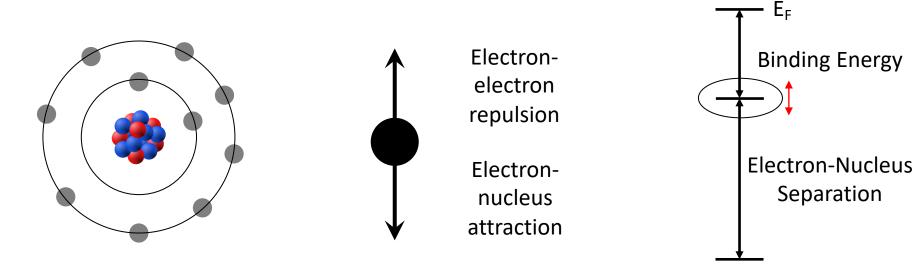
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# **XPS: Binding Energy**

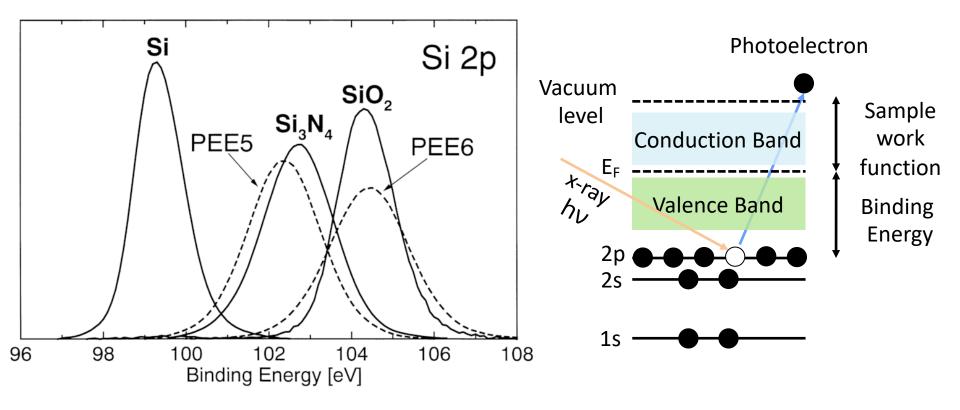


## **XPS: Local Changes to Binding Energy**



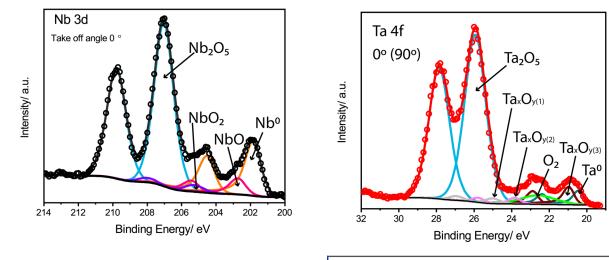


## **XPS: Local Changes to Binding Energy**



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## **Highlight: Quantifying Impurities in Nb Qubit Films**

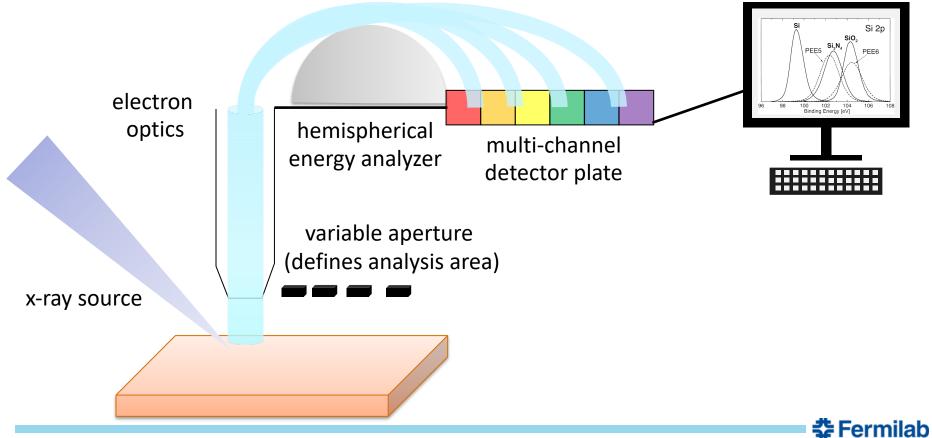


					angle		0° (90)		
angle				Species	BE/ eV	ΔBE/ eV	FWHM/ eV	Q	
Species	BE/ eV	ΔBE/ eV	FWHM/ eV	Q	Ta <sup>0</sup>	20.46	1.92	0.7	4.93
Nb <sup>0</sup>	201.83	2.7	1.1	22.06	Ta <sub>x</sub> O <sub>y(1)</sub>	20.96	1.92	0.7	6.51
NbO	202.73	2.72	1.1	6.53	$Ta_xO_{y(2)}$	23.86	1.92	0.8	1.66
NbO <sub>2</sub>	205.29	2.7	1.3	2.7	Ta <sub>x</sub> O <sub>y(3)</sub>	25.02	1.92	0.9	0.9
Nb <sub>2</sub> O <sub>5</sub>	207.03	2.76	1.3	68.7	$Ta_2O_5$	25.94	1.92	1.3	85.99
ΔBE/ eV <sub>5-0</sub>	5.2				ΔBE/ eV <sub>5-0</sub>	5.48			

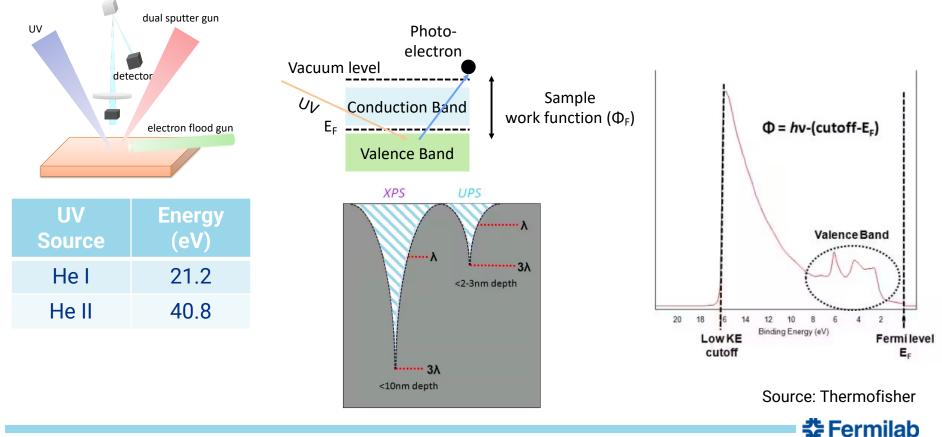


Taº

## **XPS: Electron Analyzer + Detector**

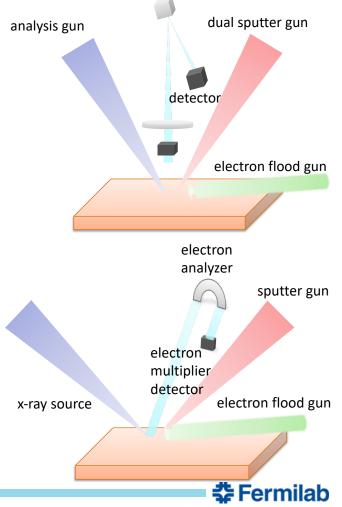


## **Related Topics: UV Photoelectron Spectroscopy**



# Summary

- ToF-SIMS
  - Very sensitive surface analytical technique
  - Allows detection of low Z elements
  - Useful for probing impurities in quantum devices
- XPS
  - Surface analytical technique sensitive to atom%
  - Allows detection of changes in bonding environment
  - Useful for characterizing surface stoichiometry in quantum devices

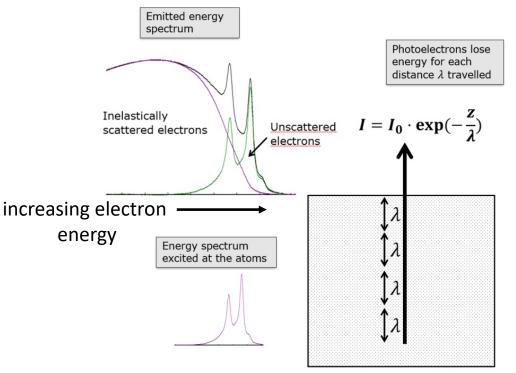


#### Appendix



#### **Inelastic Scattering**

#### Origin of variations in XPS peak-background shape



Sven Tougaard; Practical guide to the use of backgrounds in quantitative XPS. Journal of Vacuum Science & Technology A 1 January 2021; 39 (1): 011201. https://doi.org/10.1116/6.0000661

